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U.S. UTILITY Patent Application

PATENT NUMBER and
ISSUE DATE

APPL NUM 10049598	FILING DATE 02/14/2002	CLASS 264	SUBCLASS	GAU 1732	EXAMINER
**APPLICANTS: Yamaki Hiroshi;					
**CONTINUING DATA VERIFIED: This application is a 371 of PCT/JP01/04958 05/31/2000					
** FOREIGN APPLICATIONS VERIFIED: JAPAN 2000-177820 06/14/2000					
PG-PUB <input type="checkbox"/>		DO NOT PUBLISH <input type="checkbox"/>		RESCIND <input type="checkbox"/>	
Foreign priority claimed <input type="checkbox"/> yes <input type="checkbox"/> no 35 USC 119 conditions met <input type="checkbox"/> yes <input type="checkbox"/> no Verified and Acknowledged Examiners's initials				ATTORNEY DOCKET NO 0649-0835P	
TITLE : Method of injection molding of thermoplastic resin					
U.S. DEPT. OF COMM./PAT. & TM.-PTO-436L (Rev. 12-94)					

NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED	
		Total Claims	Print Claim for O.G
ISSUE FEE		DRAWING	
Amount Due	Date Paid	Sheets Drwg.	Figs. Drwg. Print Fig.
<input type="checkbox"/> TERMINAL DISCLAIMER		Application Examiner	
		PREPARED FOR ISSUE	
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